

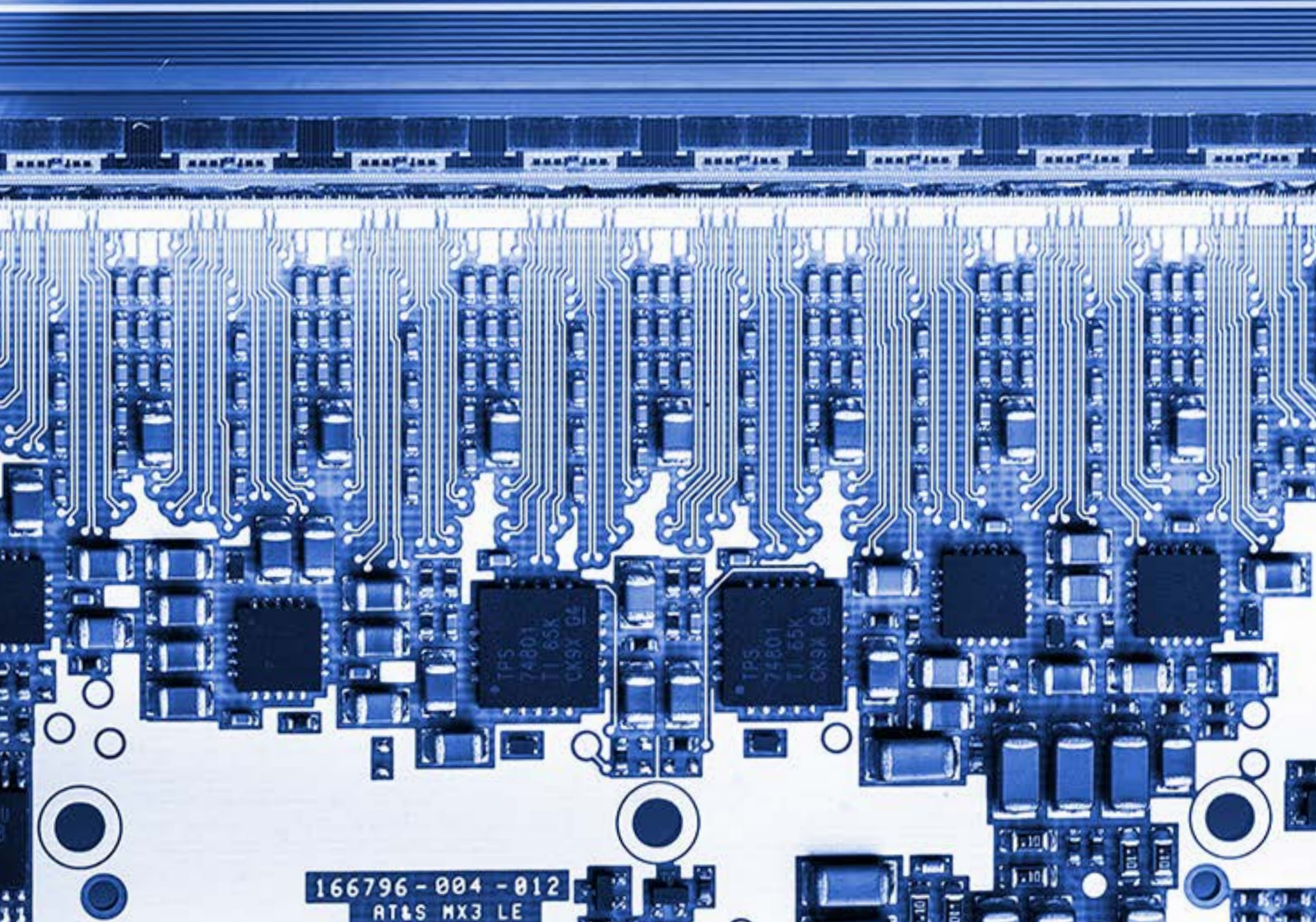
Advanced Packaging for Detectors

Applications and solutions include:

- Life science
- Metrology
- E-beam detectors

USPs:

- Application specific sensors and/or optics
- Die attach & bonding
- Ultra-high vacuum options



Advanced Packaging for Detectors

Our design and production capabilities include solutions for smallest formfactor and complex optical assemblies for imaging and photonics systems. These optoelectronic systems require critical assembly steps to reach maximum optical as well as electrical performance. These assemblies can require chip-on-board, wirebonding, gluing and placement steps for individual components such as extremely large imagers, mirrors, prisms, filters and fiber optic plates.

At Prodrive we have the capabilities to design sophisticated custom optical components. This can be applied for comprehensive illuminators with specific beam shaping capabilities or in other applications requiring high resolution color accurate lens assemblies for imagers. Regardless of your requirements we can go from concept to design and finally to series with highest quality with our automated production capabilities.

Contact us:

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